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## **Supplementary information**

## Dynamic behaviours of epoxy resin thin films during the curing process

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Figure S1. Scattering intensity profiles of the thin films obtained from the initial 100 images ( $t_w$ =390 s) and the last 100 images ( $t_w$ =3090 s) at 70 (a) and 80 C (b). No significant change in the scattering profiles depending on  $t_w$  were observed.



Figure S2. Two-dimensional profiles of scattering intensity obtained from the GI-XPCS measurement at 70 C for representative data (a), and the inplane component of the scattered wave vector (q//) (b).